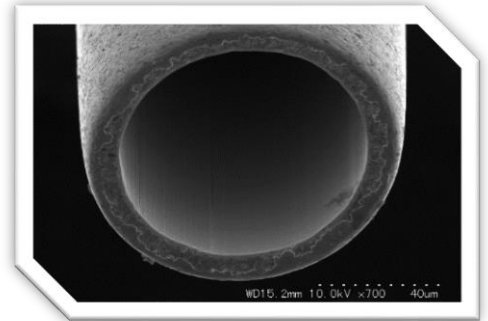


◆ Product Summary

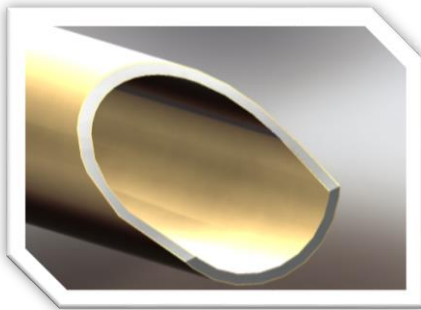
- Gold plating on the inner surface
- High conductivity and excellent sliding



SEM x700 OD ϕ 0.1xID ϕ 0.08xt0.01

◆ Features

- No flash, burr, or deformation
- Up to t0.010 mm gold plating
- Gold plating on the outer surface
- Crack resistive design
- Expanding ID by thinning pipe wall



◆ Application

- Semiconductor-inspection contact probes
- A variety of nozzles (i.e. medical dispensers)
- Micro-connectors for optical communication

◆ Standard Product

ID 0.27 × OD 0.30 × L (as desired)

◆ Specification

Material (purity)	Ni (99.99%)	Cu (99.99%)
Hardness	HV 440 ± 30	HV 220 ± 20
OD	Φ0.05~3.30 ± 0.003 mm	
ID	Φ0.04~3.20 ± 0.003 mm	
Thickness	t0.007~0.040 mm	
Length	L=0.5~15.0 ± 0.02 mm	
Gold plating	Au:Co=99.7:0.3 / t0.001-0.005 mm / HV 150 ± 20	

◆ Trial Product, Joint Development

- We make trial products as requested (3-week lead time).
- We support your project as joint development.

Please contact us for more information

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